PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT		
NATURE OF CONVEYANCE:	ASSIGNMENT		

CONVEYING PARTY DATA

Name	Execution Date
Il Kwon Shim	08/26/2004
Dario S. Filoteo Jr.	08/26/2004
Tsz Yin Ho	08/26/2004
Sebastian T. M. Soon	08/26/2004

RECEIVING PARTY DATA

Name:	STATS CHIPPAC LTD.		
Street Address:	5 Yishun St. 23		
City:	Singapore 768442		
State/Country:	SINGAPORE		

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	10931654

CORRESPONDENCE DATA

Fax Number: (408)738-0881

Correspondence will be sent via US Mail when the fax attempt is unsuccessful.

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Email: asha@ishimarulaw.com

Correspondent Name: Mikio Ishimaru

Address Line 1: The Law Offices of Mikio Ishimaru

Address Line 2: 1110 Sunnyvale-Saratoga Rd., Ste. A1

Address Line 4: Sunnyvale, CALIFORNIA 94087

NAME OF SUBMITTER: Mikio Ishimaru

Total Attachments: 3

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PATENT

REEL: 015350 FRAME: 0838

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Docket No.: 27-073

ASSIGNMENT

WHEREAS, the undersigned (hereinafter termed Assignor(s)) has/have invented certain new and useful improvements in

MULTICHIP MODULE PACKAGE AND FABRICATION METHOD

for which a United States patent application has been executed on or before the date of this assignment;

WHEREAS, <u>STATS ChipPAC Ltd.</u>, a Corporation of the <u>Republic of Singapore</u>, having a place of business at <u>5 Yishun Street 23</u>, <u>Singapore 768442</u> (hereinafter termed Assignee), is desirous of acquiring the entire right, title and interest in and to said application and said invention and improvements thereon, and in and to Letters Patents thereon when granted in the United States and foreign countries;

NOW, THEREFORE, for good and valuable consideration received by said Assignor(s) from said Assignee, the receipt of which is hereby acknowledged by said Assignor(s):

- 1. Said Assignor(s) does hereby sell, assign, transfer and convey unto said Assignee, the entire right, title and interest in and to said application and said invention and in and to any and all improvements on said invention and in and to any and all improvements on said invention heretofore or hereafter made or acquired by said Assignor(s); and in and to any and all Letters Patent on said invention and/or said improvements that may be granted in the United States or any foreign country, including each and every Letters Patent granted on any application which is a division, continuation, substitution, renewal, or continuation-in-part of any said application, and in and to each and every reissue or extension of said Letters Patent.
- 2. Said Assignor(s) hereby covenants and agrees to cooperate with said Assignee where said Assignee may enjoy to the fullest extent the right, title and interest herein conveyed. Such cooperation shall include (a) prompt execution of all papers (prepared at the expense of Assignee) which are deemed necessary or desirable by Assignee to perfect in it the right, title and interest herein conveyed, (b) prompt execution of all petitions, oaths, specifications or other papers (prepared at the expense of Assignee) which are deemed necessary or desirable by assignee for prosecuting said application, for filing and prosecuting divisional, continuation, substitution, renewal, continuation-in-part, or additional applications in the United States and/or foreign countries covering said invention and/or said improvements, for filing and prosecuting applications for reissuance of letters patent included herein, or for interference proceedings involving said invention and/or said improvements and (c) prompt assistance and cooperation in the prosecution of interference proceedings involving said invention and/or said improvements and in the adjudication of said Letters Patent, particularly by the disclosure of facts and the production of evidence relating to said invention and/or said improvements, provided the expenses which may be incurred by said Assignor(s) in lending such assistance and cooperation shall be paid by the Assignee.
- 3. The terms, covenants and conditions of this assignment shall inure to the benefit of said Assignee, its successors, assigns and/or other legal representatives and shall be binding upon said Assignor(s), his/her heirs, legal representatives and assigns.
- 4. Said Assignor(s) hereby warrants and represents that he/she has not entered into any assignment, contract or understanding in conflict herewith.

PATENT REEL: 015350 FRAME: 0839

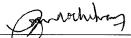
IN	WITNESS	WHEREOF,	the said	Assignor	has	executed	and	delivered	this	instrument	on
	date set for			_							

Sh	<u>`</u>

IL Kwon Shim

26-	Aug	 2004
Doto		

Date



Witness Signature

MARIMUTHY PANDS CHEVRYM

Print Witness Name

IN WITNESS WHEREOF, the said Assignor has executed and delivered this instrument on the date set forth below.

Dario S. Filoteo J

MERILO LEO

Print Witness Name

26 - August - 2000

Print Witness Name

26- AUGUST- 2004

IN WITNESS WHEREOF, the said Assignor has executed and delivered this instrument on the date set forth below.

Tsz Yin Ho

Date

Witness Signature

RACHEL L- ABMAN Print Witness Name

Lee Kyan Fang Print Witness Name

26- August 2004 Date

26 Aug '04

Docket No.: 27-073 **ASSIGNMENT**

IN WITNESS WHEREOF, the said Assignor has executed and delivered this instrument on the date set forth below.

Sebastian T.M. Soon

Witness Signature

Emmanuel Print Witness Name

26/08/04

26/08/04

Date

Date

PATENT REEL: 015350 FRAME: 0841

RECORDED: 11/10/2004